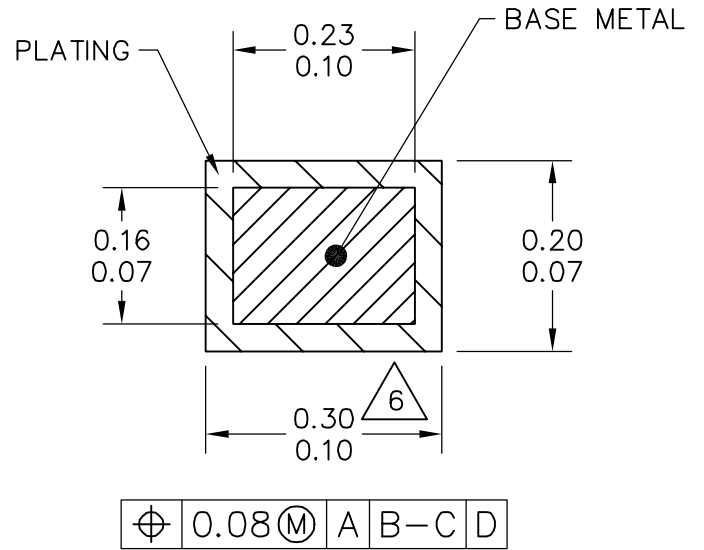
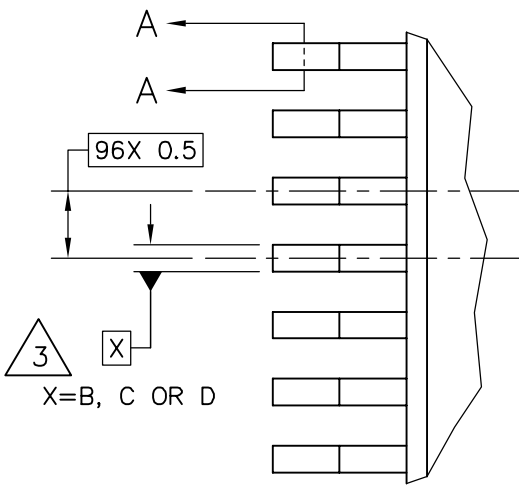


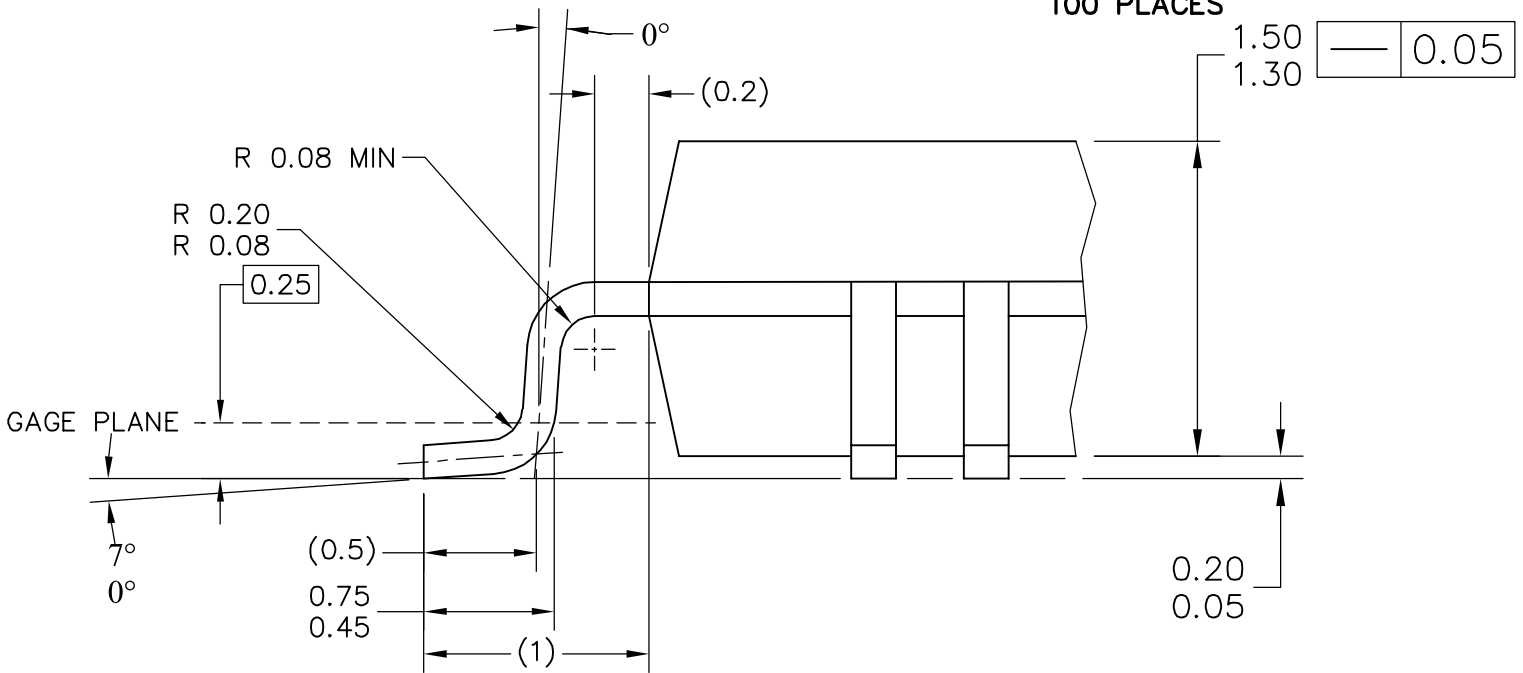
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TITLE: 100 LEAD LQFP 14 X 14, 0.5 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23308W	REV: H	
	CASE NUMBER: 983-02	25 MAY 2005	
	STANDARD: NON-JEDEC		



SECTION A-A

ROTATED 90° CW
100 PLACES

VIEW A



VIEW B

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DATUMS B, C AND D TO BE DETERMINED AT DATUM PLANE H.

4. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY A MAXIMUM OF 0.1 mm.

5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSIONS. THE MAXIMUM ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

6. DIMENSION b DOES NOT INCLUDE DAM BAR PROTRUSION. PROTRUSIONS SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL BE 0.07 MM.

7. DIMENSIONS D AND E ARE DETERMINED AT THE SEATING PLANE, DATUM A.

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